

Product Change Notice

Issue Date: July 26, 2017

Change Type:

- Assembly site addition (Amkor China).

Parts Affected:

Device	Package Size	Package	Pin Count
BCM5761B0KFBGH	12X12	FBGA	121
BCM5761SB0KFBG	12X12	FBGA	121
BCM5761B0KFBG	12X12	FBGA	121
BCM5880PKFBG	13x13	FBGA	225
BCM5751KFBG	15X15	FBGA	196
BCM5396KFBG	17X17	FBGA	256
BCM5396IFBG	17X17	FBGA	256
BCM5396KFB1	17X17	FBGA	256
BCM5396KFB	17X17	FBGA	256

Description and Extent of Change:

- Add Amkor China as an additional assembly supplier for the above devices.
- The extent of the change is minimal. Amkor China has internally qualified the package type is in volume production for the above package technology

Reasons for Change:

- Manufacturing flexibility

Effect of Change on Fit, Form, Function, Quality, or Reliability:

- No impact on form, fit and function

Effective Date of Change:

- Product shipments using this change will begin week of September 29, 2017

Qualification Data:
Pkg Qualification Reference# PQ00896

Fab Technology : 130nm G
 Package Type : FBGA
 Package Size : 14mm x 14mm
 Lead Count : 256
 Bond Wire : GOLD: 99.99% Au (4N)

Stress Test	Condition	Read points Cycles / Hrs.	Sample Size	Requirements	Results (# fail/ss)
Precondition	MSL3 JESD22-A113E		228 units	0 failures	0 / 228
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	76 units	0 failures	0 / 76
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106 Cond C	500 cycles	76 units	0 failures	0 / 76
uHast	130° C/85%RH/ JEDEC Std. 22-A102-C	96hrs	76 units	0 failures	0 / 76
HTSL	TA=150° C JEDEC Std. 22-A103-C	1000hrs	76 units	0 failures	0 / 76

Pkg Qualification Reference# PQ01437

Fab Technology : 65nm LP
 Package Type : FBGA
 Package Size : 21mm x 21mm
 Lead Count : 400
 Bond Wire : GOLD: 99.99% Au (4N)

Stress Test	Condition	Read points Cycles / Hrs.	Sample Size	Requirements	Results (# fail/ss)
Precondition	MSL3 JESD22-A113E		152 units	0 failures	0 / 152
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	76 units	0 failures	0 / 76
uHast	130° C/85%RH/ JEDEC Std. 22-A102-C	96hrs	76 units	0 failures	0 / 76
HTSL	TA=150° C JEDEC Std. 22-A103-C	1000hrs	76 units	0 failures	0 / 76

Pkg Qualification Reference# PQ02194

Fab Technology : 65nm LP
 Package Type : FBGA
 Package Size : 17mm x 17mm
 Lead Count : 318
 Bond Wire : GOLD: 99% Au/1% Pd (2N)

Stress Test	Condition	Read points Cycles / Hrs.	Sample Size	Requirements	Results (# fail/ss)
Precondition	MSL3 JEDEC Std. A113E		260 units	0 failures	0 / 260
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	76 units	0 failures	0 / 76
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106 Cond C	500 cycles	76 units	0 failures	0 / 76
uHast	130° C/85%RH/ JEDEC Std. 22-A102-C	96hrs	76 units	0 failures	0 / 76
HTSL	TA=150° C JEDEC Std. 22-A103-C	1000hrs	76 units	0 failures	0 / 76

Pkg Qualification Reference# PQ03045

Fab Technology : 40nm LP
 Package Type : FBGA
 Package Size : 10mm x 10mm
 Lead Count : 196
 Bond Wire : COPPER: 99.95% Cu/Pd-plated (3N, NMC)

Stress Test	Condition	Read points Cycles / Hrs.	Sample Size	Requirements	Results (# fail/ss)
Precondition	MSL3 JEDEC Std. A113E		260 units	0 failures	0 / 260
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	77 units	0 failures	0 / 77
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106 Cond C	300 cycles	77 units	0 failures	0 / 77
uHast	130° C/85%RH/ JEDEC Std. 22-A102-C	96hrs	77 units	0 failures	0 / 77
HTSL	TA=150° C JEDEC Std. 22-A103-C	1000hrs	77 units	0 failures	0 / 77

Pkg Qualification Reference# PQ01843

Fab Technology : 65nm LP
 Package Type : FBGA
 Package Size : 17mm x 17mm
 Lead Count : 400
 Bond Wire : COPPER: 99.95% Cu/Pd-plated (3N, NMC)

Stress Test	Condition	Read points Cycles / Hrs.	Sample Size	Requirements	Results (# fail/ss)
Precondition	MSL3 JESD22-A113E		260 units	0 failures	0 / 260
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	76 units	0 failures	0 / 76
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106 Cond C	500 cycles	76 units	0 failures	0 / 76
uHast	130° C/85%RH/ JEDEC Std. 22-A102-C	96hrs	76 units	0 failures	0 / 76
HTSL	TA=150° C JEDEC Std. 22-A103-C	1000hrs	76 units	0 failures	0 / 76

Pkg Qualification Reference# PQ01925

Fab Technology : 65nm LP
 Package Type : FBGA
 Package Size : 8mm x 8mm
 Lead Count : 81
 Bond Wire : COPPER: 99.95% Cu/Pd-plated (3N, NMC)

Stress Test	Condition	Read points Cycles / Hrs.	Sample Size	Requirements	Results (# fail/ss)
Precondition	MSL3 JESD22-A113E		260 units	0 failures	0 / 260
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	76 units	0 failures	0 / 76
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106 Cond C	500 cycles	76 units	0 failures	0 / 76
uHast	130° C/85%RH/ JEDEC Std. 22-A102-C	96hrs	76 units	0 failures	0 / 76
HTSL	TA=150° C JEDEC Std. 22-A103-C	1000hrs	76 units	0 failures	0 / 76

Pkg Qualification Reference# PQ01745

Fab Technology : 65nm LP
 Package Type : FBGA
 Package Size : 12mm x 12mm
 Lead Count : 213
 Bond Wire : COPPER: 99.95% Cu/Pd-plated (3N, NMC)

Stress Test	Condition	Read points Cycles / Hrs.	Sample Size	Requirements	Results (# fail/ss)
Precondition	MSL3 JEDEC Std. A113E		260 units	0 failures	0 / 260
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	76 units	0 failures	0 / 76
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106 Cond C	500 cycles	76 units	0 failures	0 / 76
uHast	130° C/85%RH/ JEDEC Std. 22-A102-C	96hrs	76 units	0 failures	0 / 76
HTSL	TA=150° C JEDEC Std. 22-A103-C	1000hrs	76 units	0 failures	0 / 76

Pkg Qualification Reference# PQ01588

Fab Technology : 65nm LP
 Package Type : FBGA
 Package Size : 14mm x 14mm
 Lead Count : 169
 Bond Wire : COPPER: 99.95% Cu/Pd-plated (3N, NMC)

Stress Test	Condition	Read points Cycles / Hrs.	Sample Size	Requirements	Results (# fail/ss)
Precondition	MSL3 JEDEC Std. A113E		240 units	0 failures	0 / 240
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	76 units	0 failures	0 / 76
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106 Cond C	500 cycles	76 units	0 failures	0 / 76
uHast	130° C/85%RH/ JEDEC Std. 22-A102-C	96hrs	76 units	0 failures	0 / 76
HTSL	TA=150° C JEDEC Std. 22-A103-C	1000hrs	76 units	0 failures	0 / 76

Pkg Qualification Reference# PQ03397

Fab Technology : 28nm HPM
 Package Type : FBGA
 Package Size : 21mm x 21mm
 Lead Count : 400
 Bond Wire : COPPER: 99.95% Cu/Pd-plated (3N, NMC)

Stress Test	Condition	Read points Cycles / Hrs.	Sample Size	Requirements	Results (# fail/ss)
Precondition	MSL3 JEDEC Std. A113E		260 units	0 failures	0 / 260
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	77 units	0 failures	0 / 77
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106 Cond C	300 cycles	77 units	0 failures	0 / 77
uHast	130° C/85%RH/ JEDEC Std. 22-A102-C	96hrs	77 units	0 failures	0 / 77
HTSL	TA=150° C JEDEC Std. 22-A103-C	1000hrs	77 units	0 failures	0 / 77

Please contact your Broadcom Limited field sales engineer or Contact Center for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.